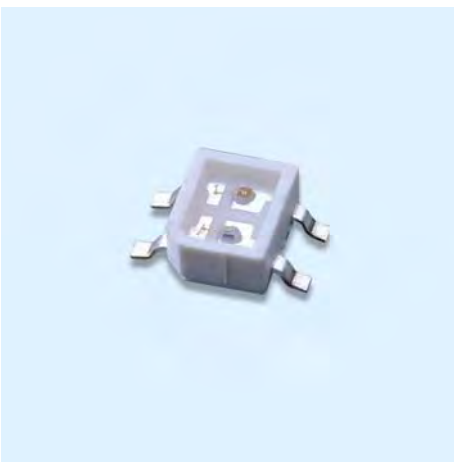


SMD ■ LED EAPL3427RGA0



Features

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Applications

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Device Selection Guide

Chip		Emitted Color	Resin Color
Type	Material		
SUR	AlGaInP	Brilliant Red	Water Clear
SYG	AlGaInP	Brilliant Yellow Green	

Absolute Maximum Ratings @Ta=25°C

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	SUR	25
		SYG	
Peak Forward Current (Duty 1/10 @ 1KHz)	I_{FP}	SUR	60
		SYG	
Power Dissipation	P_d	SUR	60
		SYG	
Electrostatic Discharge(HBM)	ESD	2000	V
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics @ Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	SUR	17	41	-----	mcd I _F =20mA
		SYG	11	17	-----	
Viewing Angle	2θ1/2	-----	130	-----	deg	I _F =20mA
Peak Wavelength	λ _p	SUR	-----	632	-----	nm I _F =20mA
		SYG	-----	575	-----	
Dominant Wavelength	λ _d	SUR	-----	624	-----	nm I _F =20mA
		SYG	-----	573	-----	
Spectrum Radiation Bandwidth	Δλ	SUR	-----	20	-----	nm I _F =20mA
		SYG	-----	20	-----	
Forward Voltage	V _F	SUR	-----	2.0	2.4	V I _F =20mA
		SYG	-----	2.0	2.4	
Reverse Current	I _R	-----	-----	10	μA	V _R =5V

Reliability Test Items and Conditions

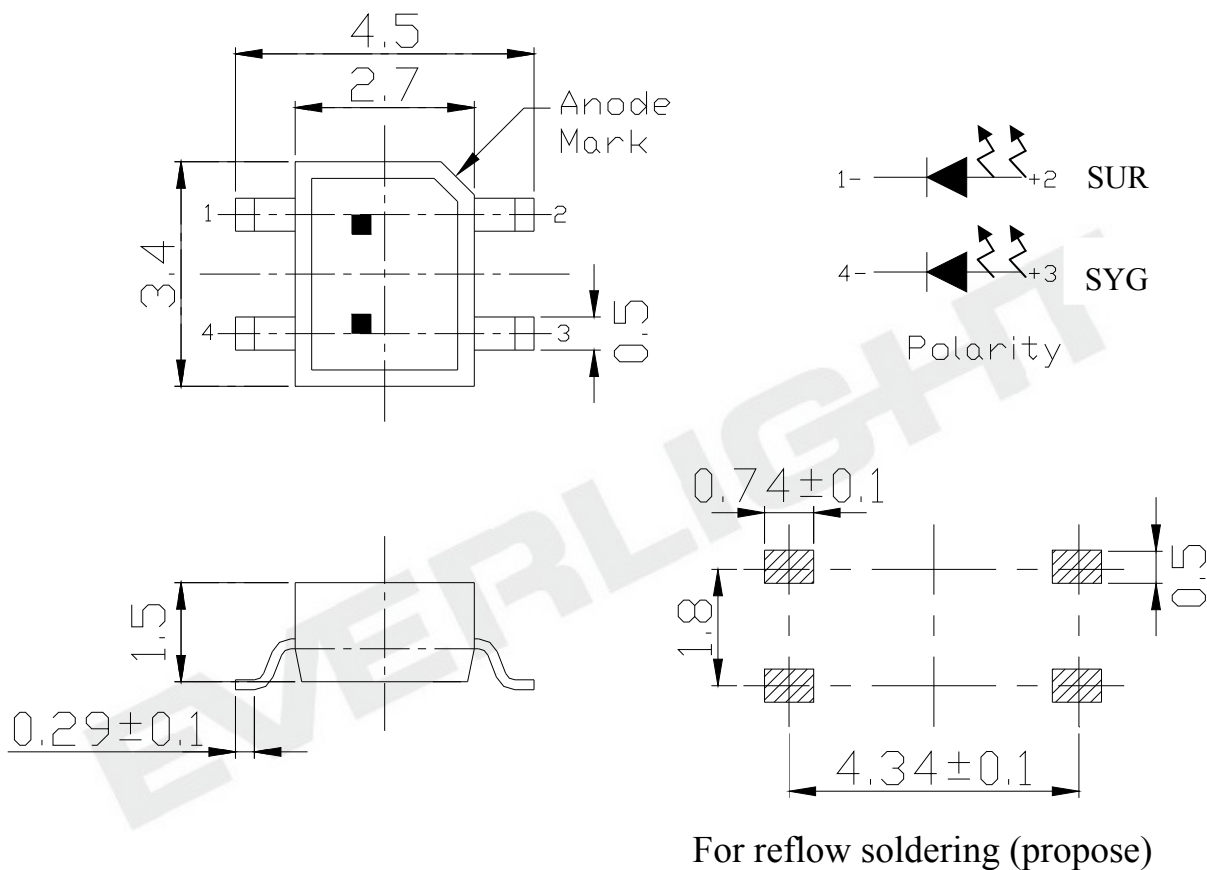
The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5sec.	6 min	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I _F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

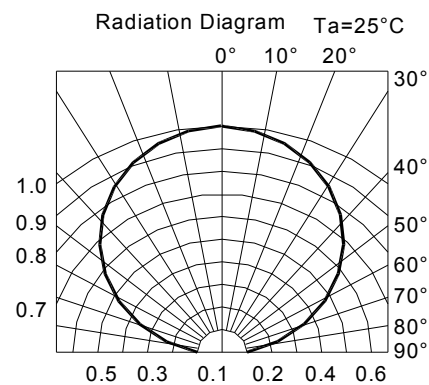
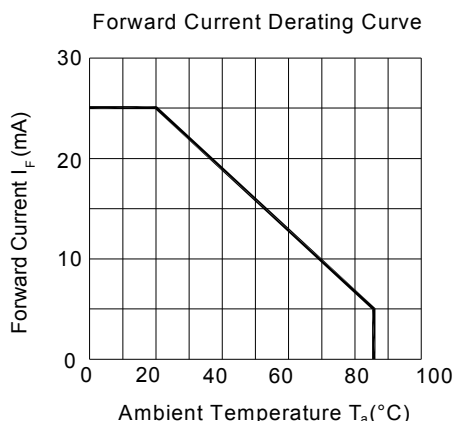
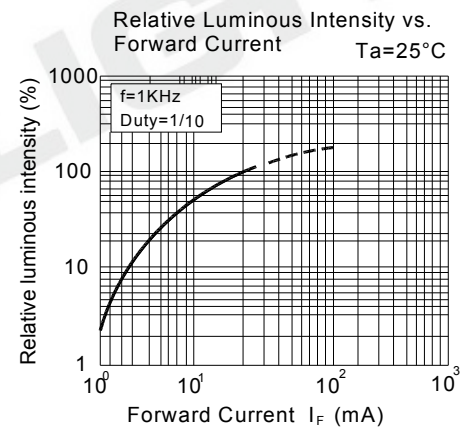
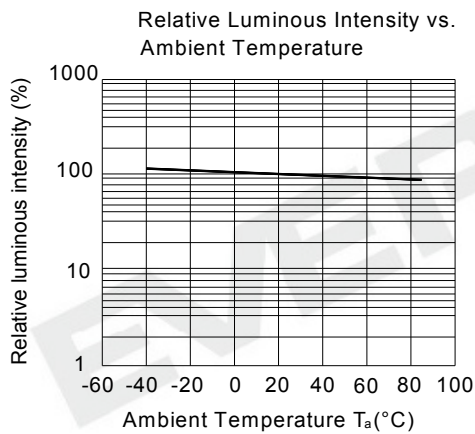
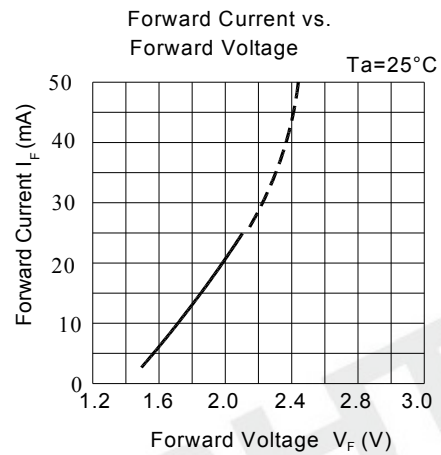
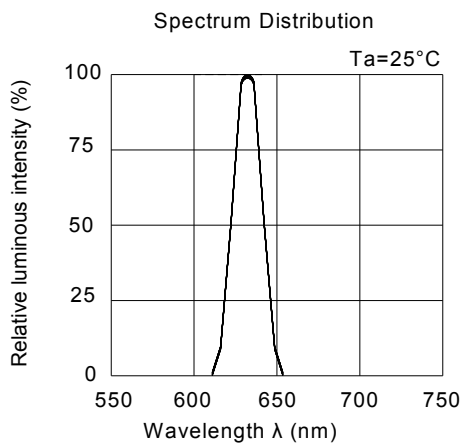
Package Dimensions



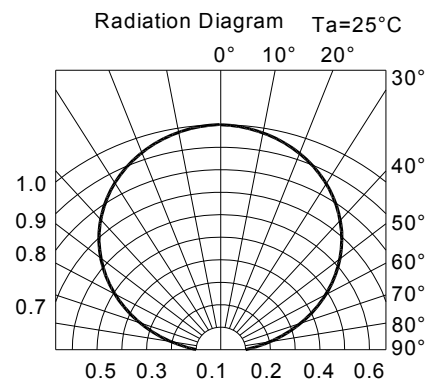
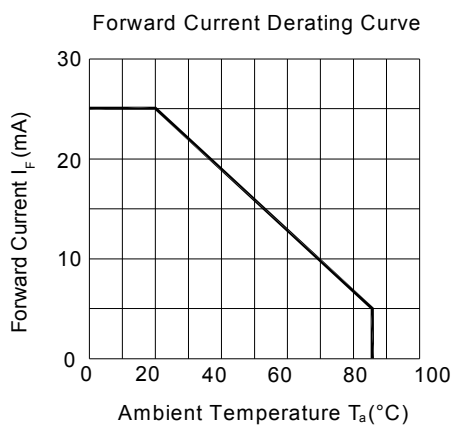
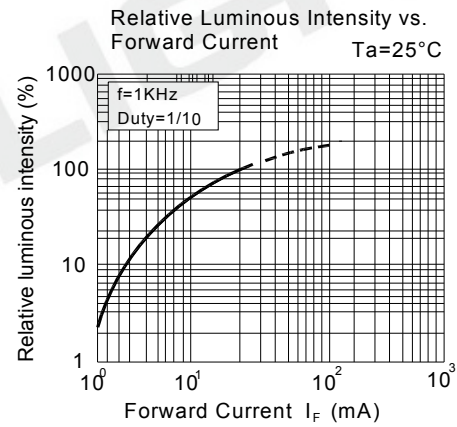
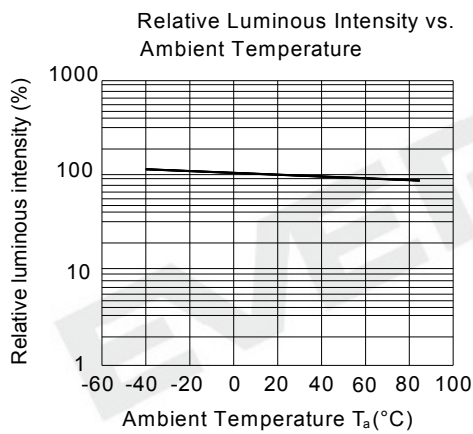
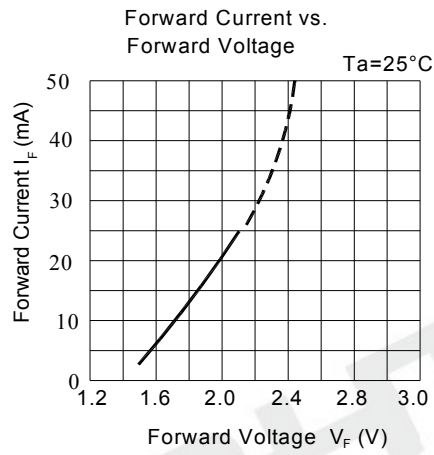
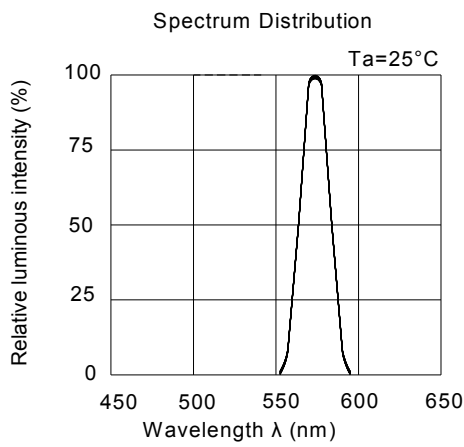
For reflow soldering (propose)

- Notes:**
1. All dimensions are in millimeters.
 2. Tolerance unless mentioned is ± 0.1 mm.

Typical Electro-Optical Characteristics Curves(SUR)



Typical Electro-Optical Characteristics Curves(SYG)

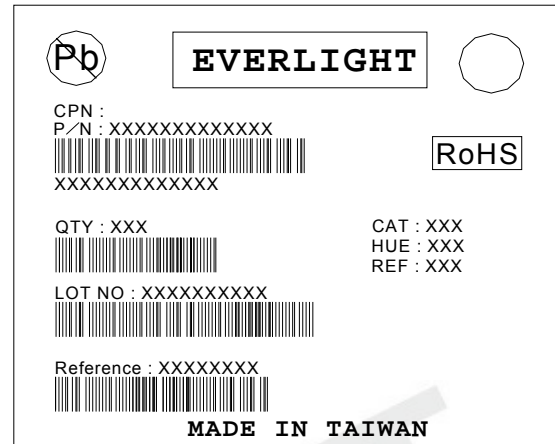


Label Explanation

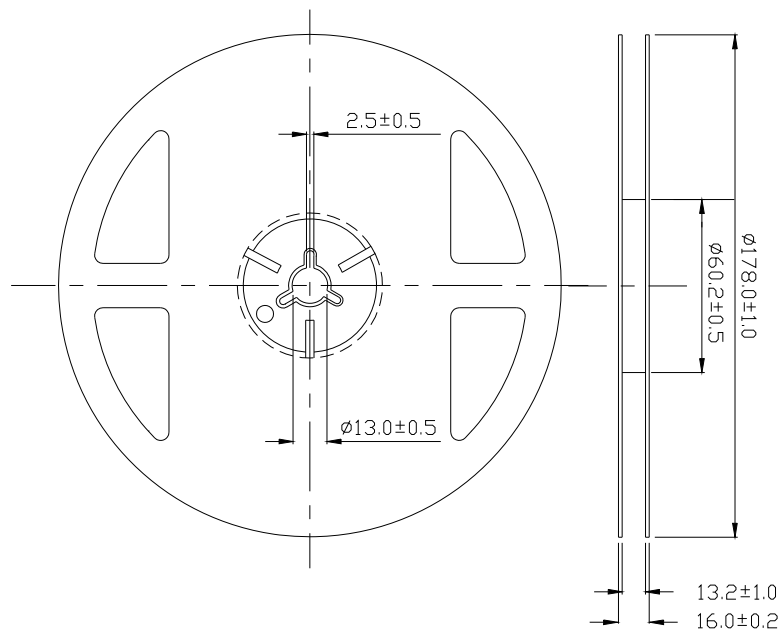
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank

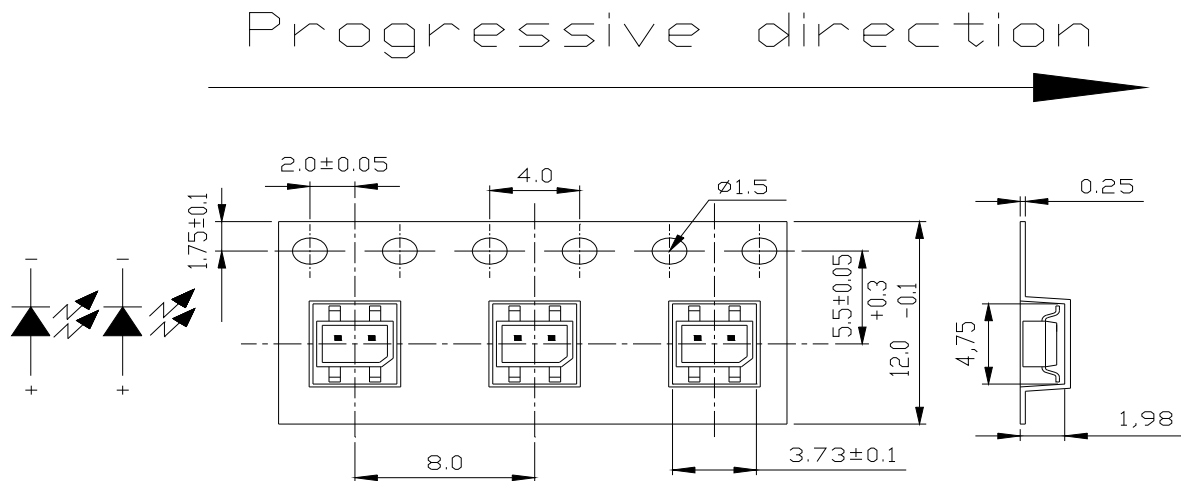


Reel Dimensions



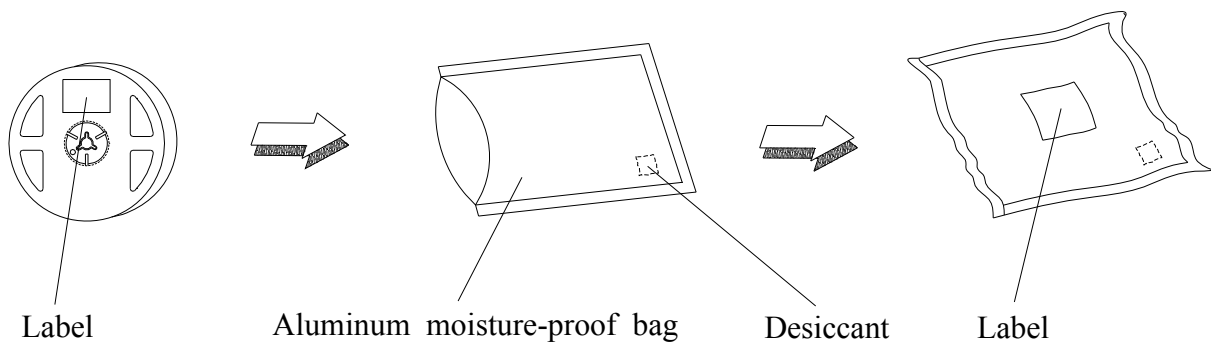
Note: Tolerance unless mentioned is ± 0.1 mm; Unit = mm

Carrier Tape Dimensions: Loaded quantity per reel 1000 PCS/reel



Note: Tolerance unless mentioned is ± 0.1 mm; Unit = mm

Moisture Resistant Packaging



Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

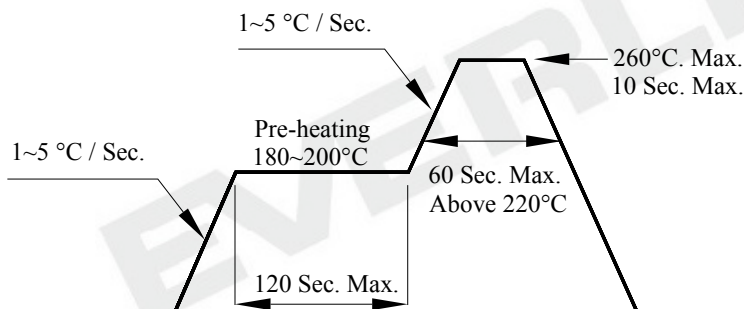
2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

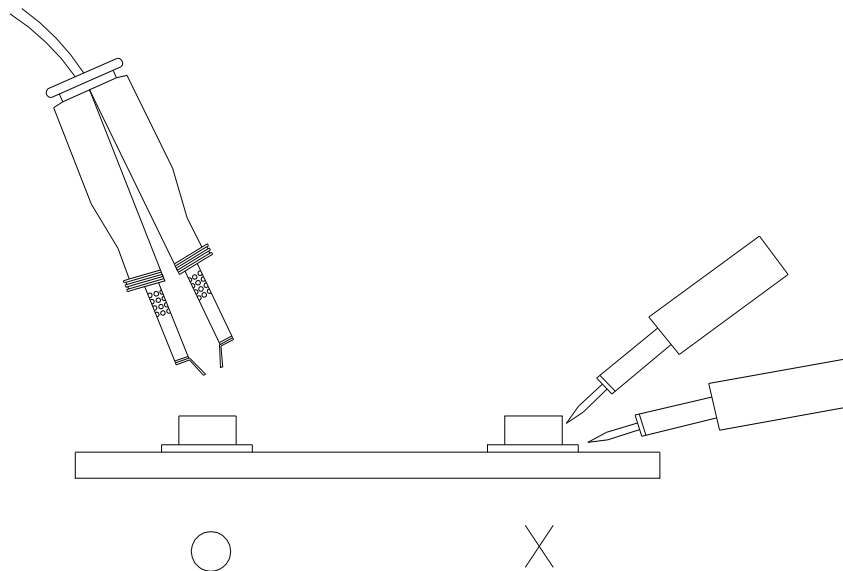
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



DISCLAIMER

1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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